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IEEE R10 TENSYP 2027 12-14 May 2027 at the Faculty of Engineering, University of Peradeniya, Sri Lanka

Web : <https://tensymp27.ieee.lk/>

CALL FOR PAPERS

Theme : Connected Intelligence for Resilient Societies

Hosted in Sri Lanka for the first time, TENSYP 2027 highlights the IEEE Sri Lanka Section's growing research and innovation leadership in the Asia-Pacific region and reflects the region's commitment to responsible, resilient, and inclusive technological advancement.

About the Symposium

TENSYP 2027, the IEEE Region 10 Symposium, is a flagship international technical forum of IEEE Region 10 (Asia-Pacific). The region comprises 60 Sections, 6 Councils, and 42 Subsections, spanning some of the world's most dynamic and rapidly evolving innovation ecosystems.

The symposium provides a high-level platform for researchers, academics, students, industry leaders, innovators, and policymakers to exchange ideas, present research findings, and discuss future directions across electrical, electronic, computer engineering, and information technologies.

In addition to technical paper sessions, TENSYP 2027 will feature:

- Distinguished keynote addresses from global technology leaders
- Special sessions on emerging interdisciplinary themes
- Industry forums and technology showcases
- Student and Young Professional activities
- IEEE Region 10 leadership engagement
- Networking and collaboration opportunities across Asia-Pacific

Call for Papers

Full papers (4-6 pages, IEEE double-column format) are invited in, but not limited to, the following areas:

- Artificial Intelligence, Machine Learning, and Data Intelligence
- Future Communication and Networking Technologies
- Cyber-Physical Systems, IoT, and Intelligent Automation
- Sustainable Energy and Environmental Technologies
- Cybersecurity, Privacy, and Resilient Computing
- Technology for Health, Humanity, and Society
- Ethics, Policy, and Governance in Connected Systems
- Education and Capacity Building in Resilient Technologies

Submissions should present original research contributions, innovative applications, case studies, or emerging research directions aligned with the symposium theme.

Accepted and presented papers will be submitted for inclusion in IEEE Xplore, subject to IEEE quality and scope requirements.

Why Sri Lanka?

Located in the heart of the Indian Ocean, Sri Lanka serves as a strategic bridge between South Asia and Southeast Asia. The University of Peradeniya, Sri Lanka's premier engineering institution, provides an academic environment that integrates research excellence with multidisciplinary collaboration.

TENSYP 2027 will offer participants both a rigorous technical experience and meaningful regional engagement within one of the fastest-growing IEEE regions globally.

IMPORTANT DATES

Special Sessions (workshops, tutorials, etc)

Opening Submissions: 15 July 2026
Submission Deadline: 1 September 2027
Notification of Acceptance: 28 September 2027

Conference

Opening Submissions: 7 October 2026
Paper Submission Deadline: 7 January 2027
Notification of Acceptance: 7 March 2027
Camera Ready Submission: 31 March 2027
Symposium Dates: 12-14 May 2027



Contact :

Conference Secretary:
Dr. Upul Jayasinghe,
University of Peradeniya, Sri Lanka
Email: tensymp27@eng.pdn.ac.lk

Organized by



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